

FIG.1

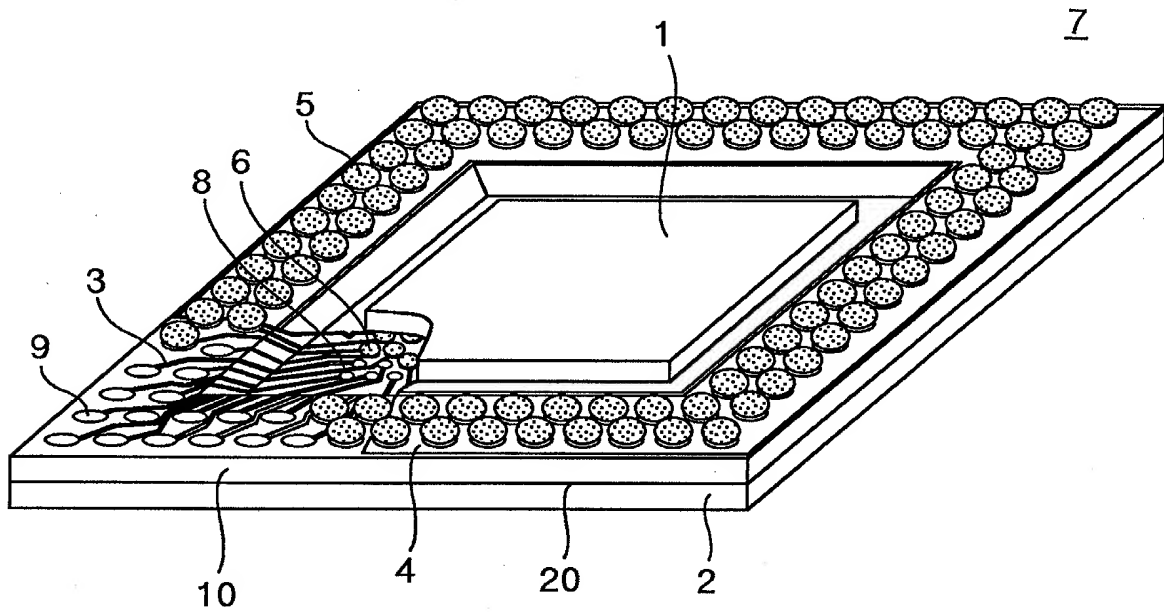


FIG.2

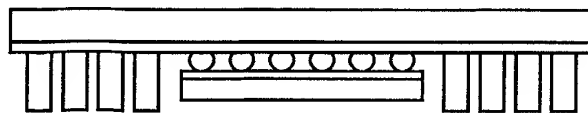


FIG.3

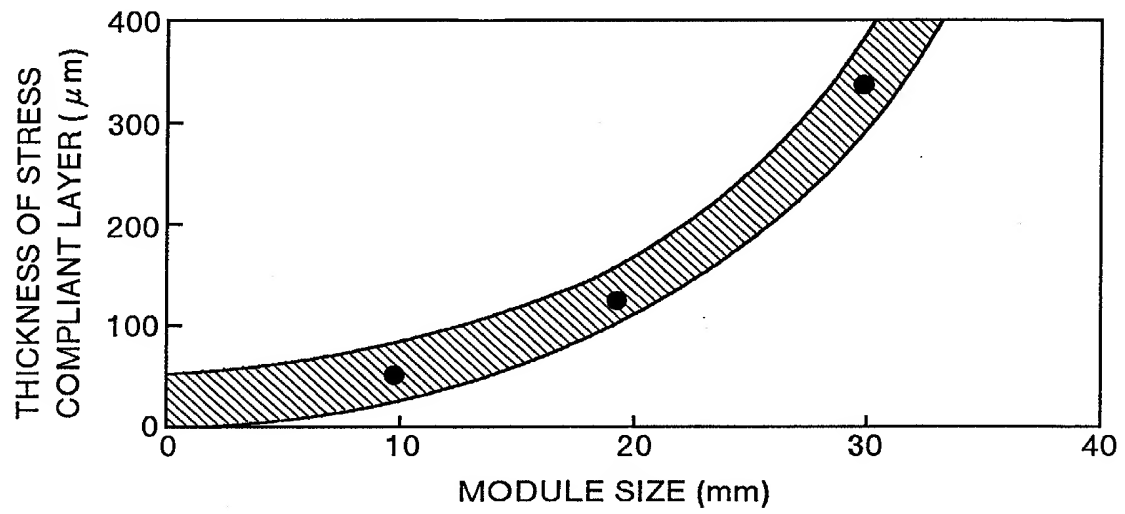


FIG.4A

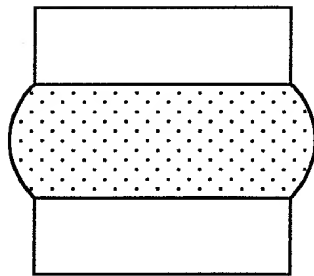


FIG.4B

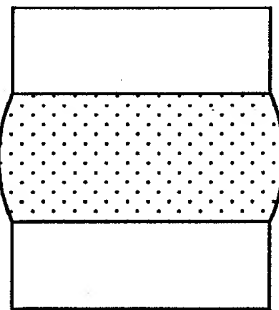


FIG.4C

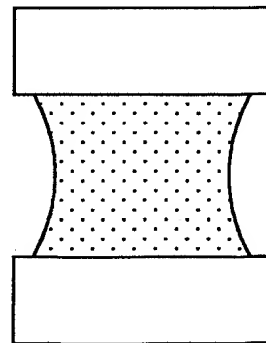
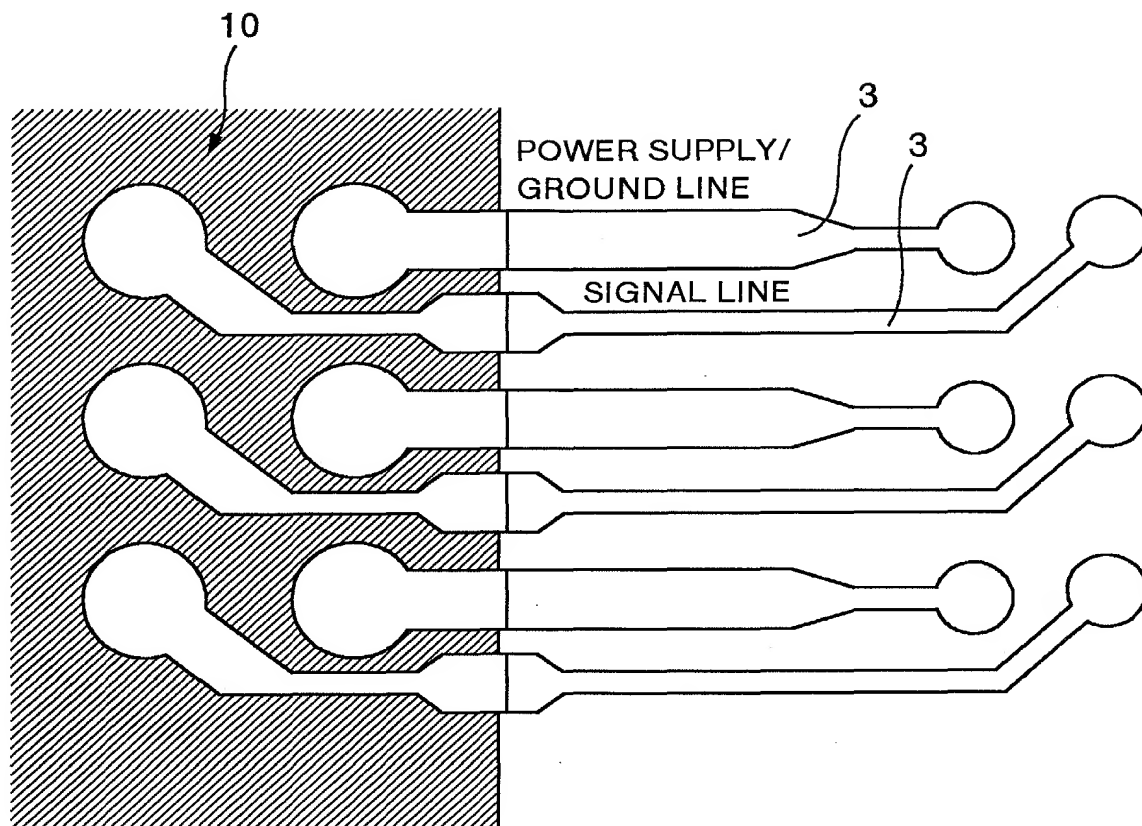


FIG.5



403433 244660

FIG.6

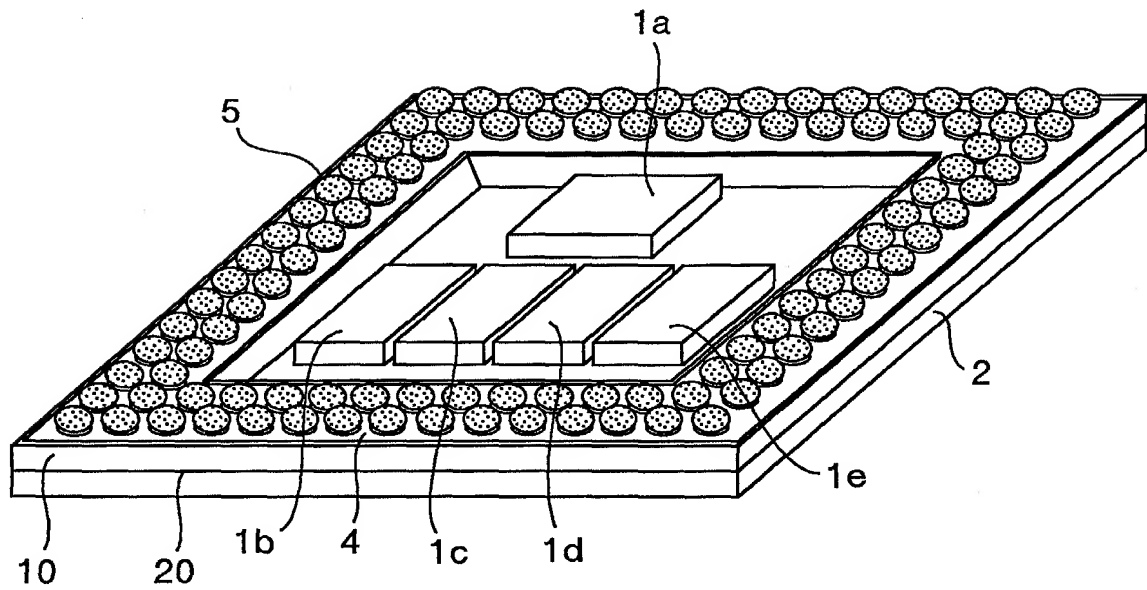


FIG.7

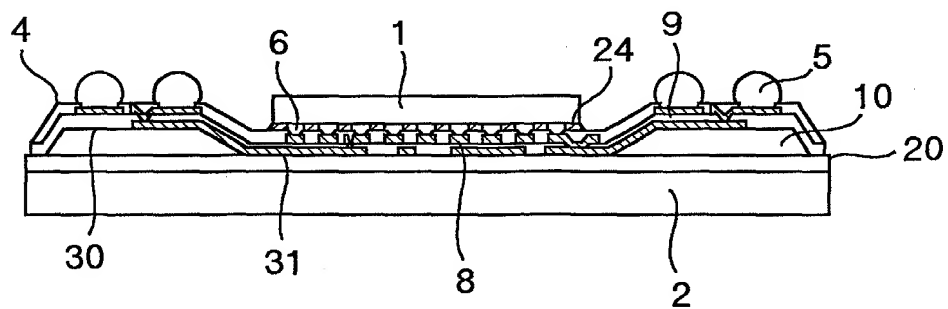


FIG.8A

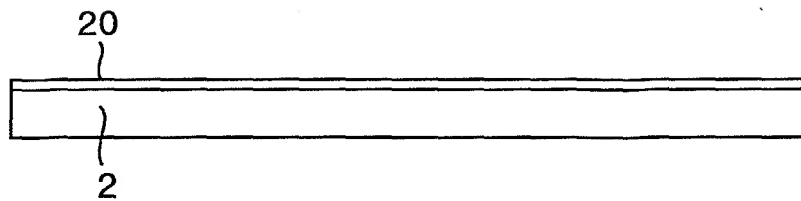


FIG.8B

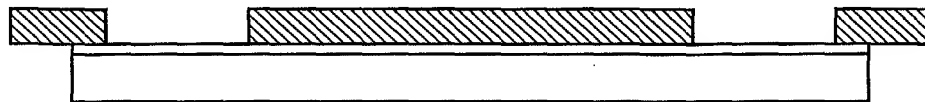


FIG.8C

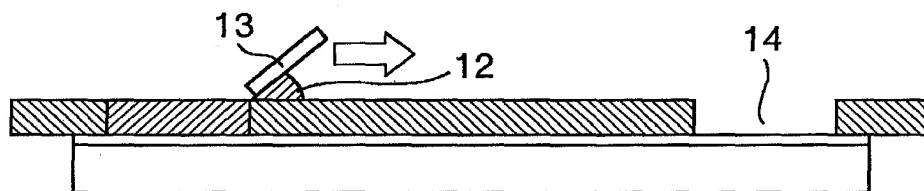


FIG.8D

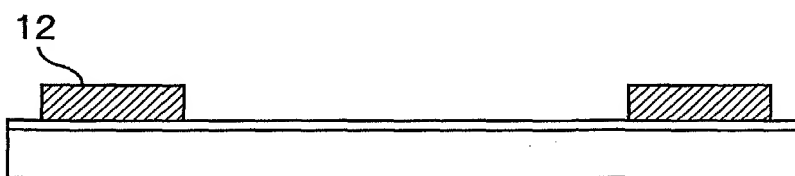


FIG.8E

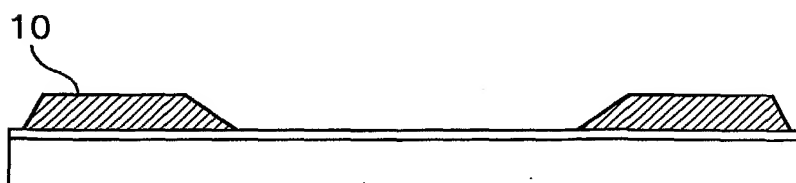


FIG.8F

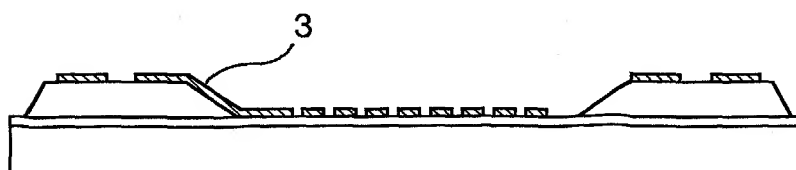


FIG. 8A

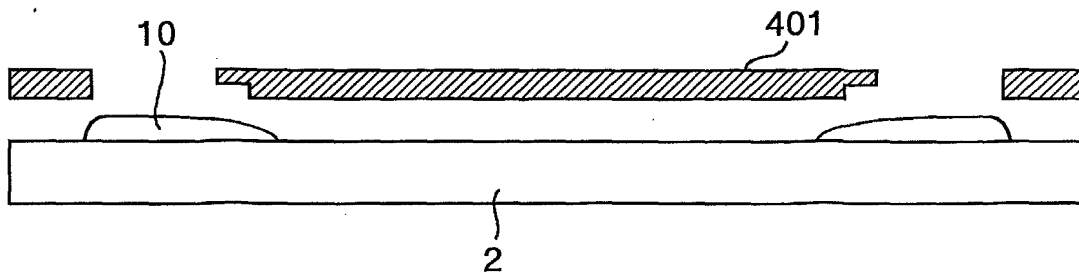
[illegible]

FIG.11

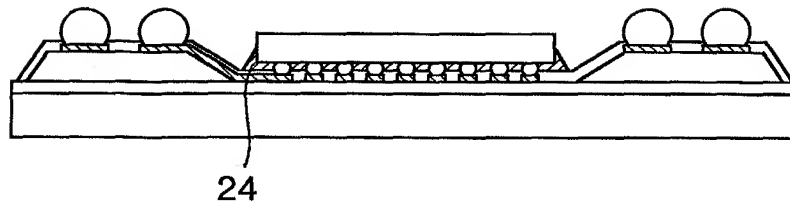


FIG.12

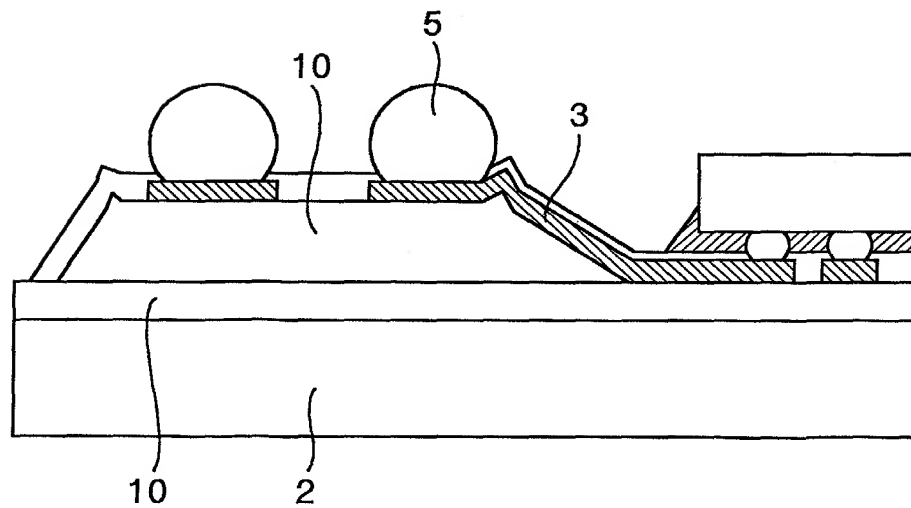


FIG. 13

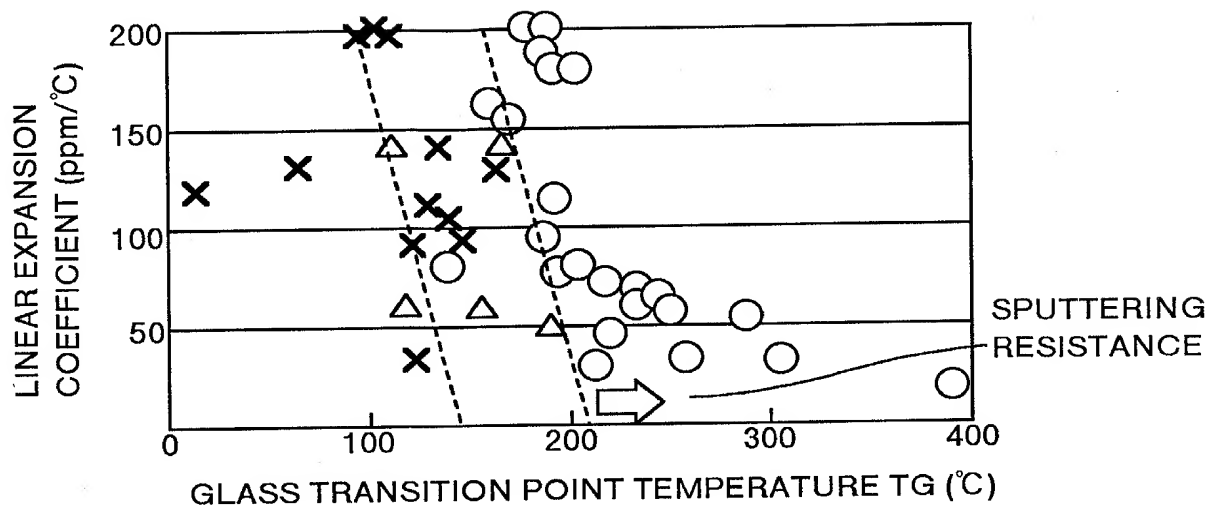


FIG. 14

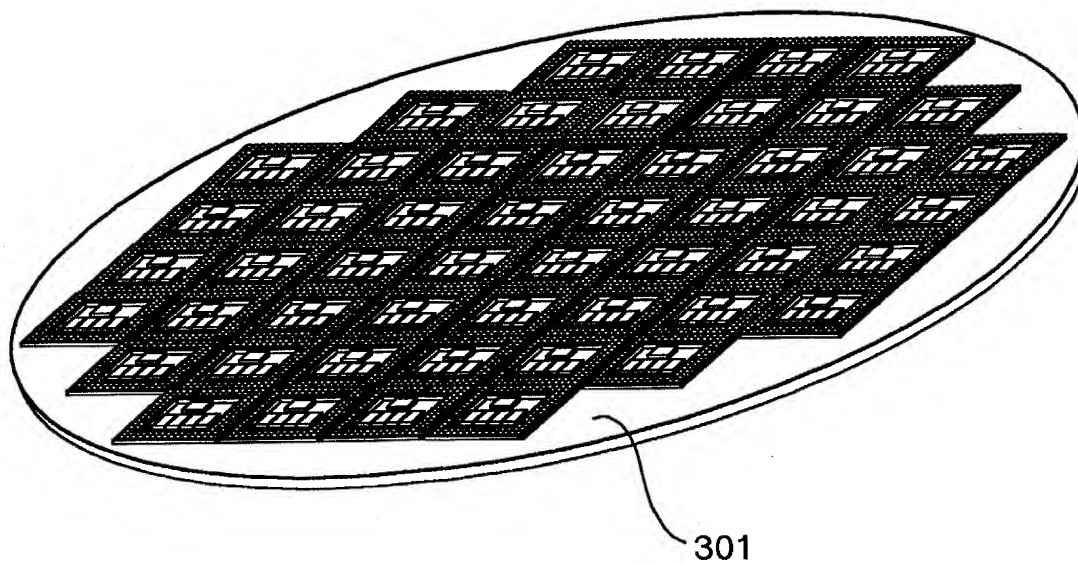


FIG.15

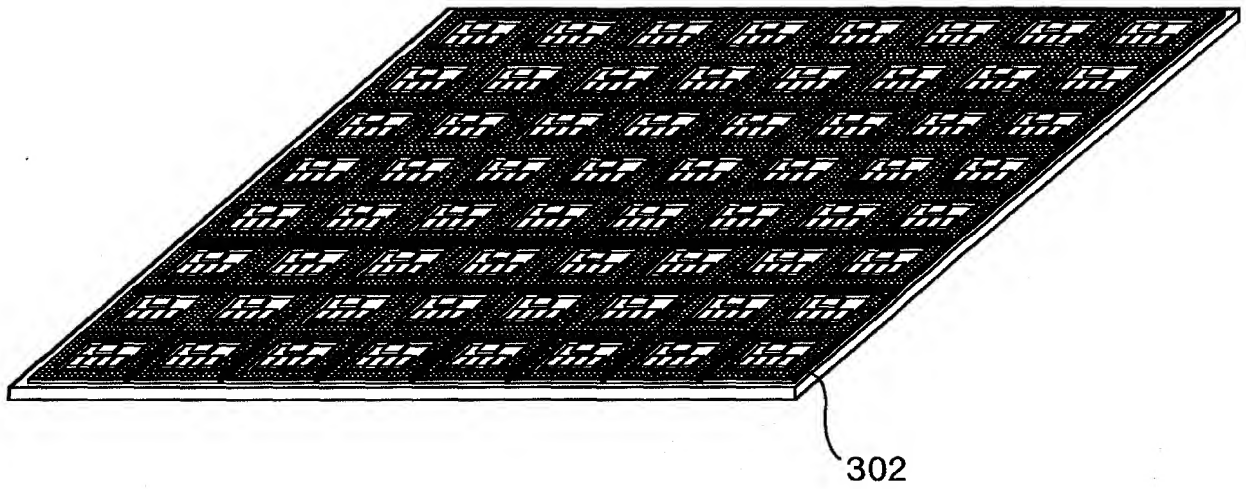


FIG.16

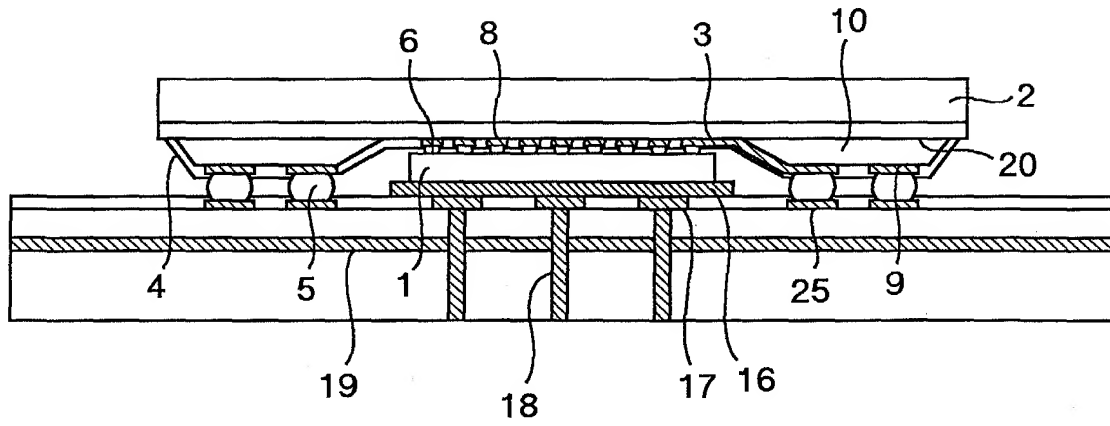
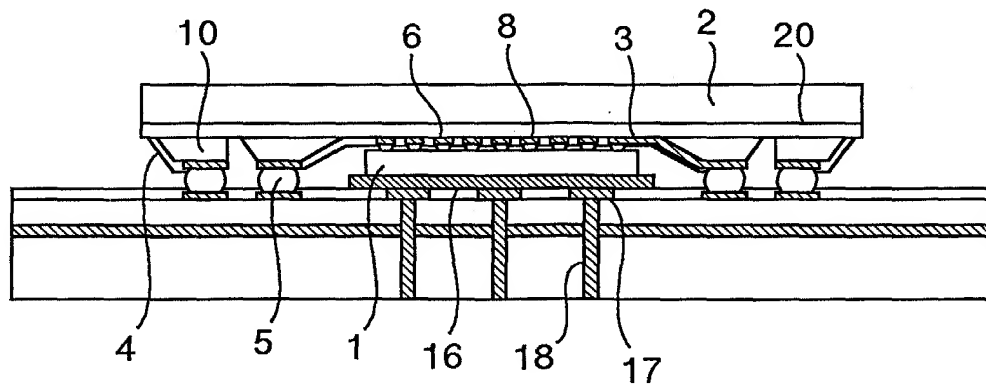


FIG.17



15-00000

FIG.18

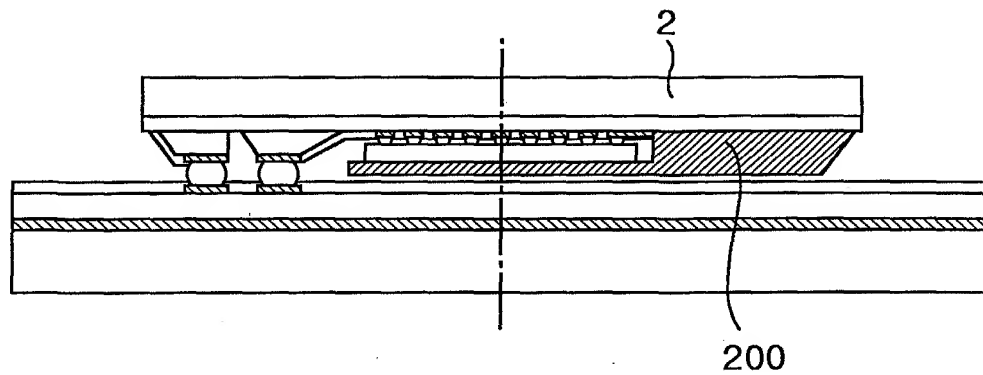


FIG.19

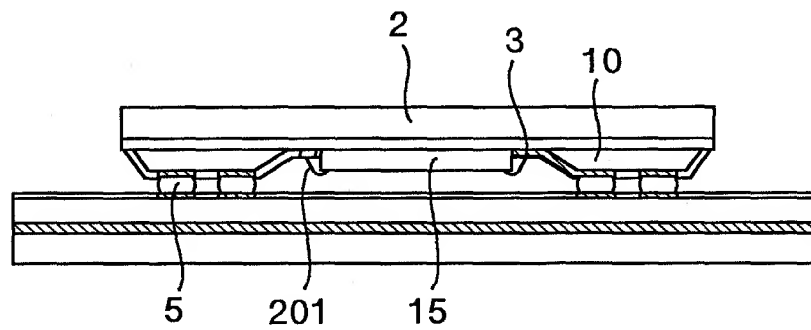
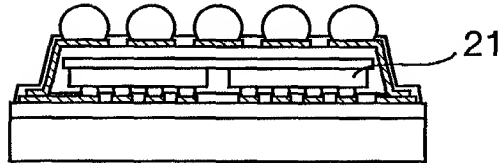


FIG.22



105120 6610660

FIG.23A

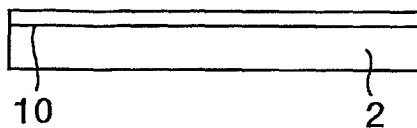


FIG.23B



FIG.23C

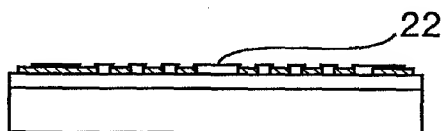


FIG.23D

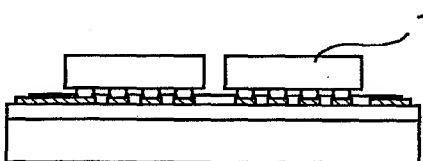


FIG.23E

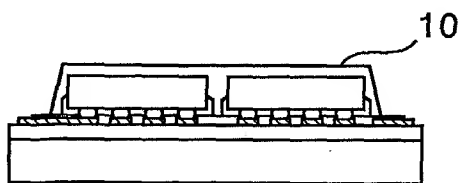


FIG.23F



FIG.23G

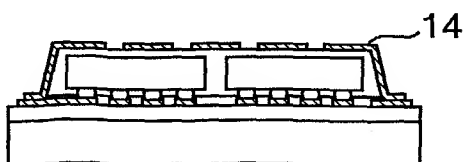


FIG.24A

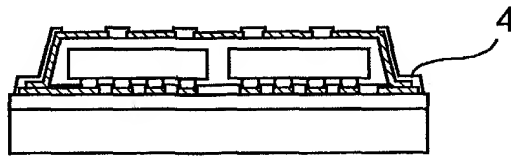


FIG.24B

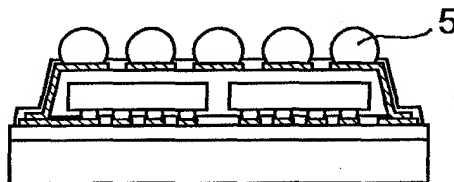


FIG.25

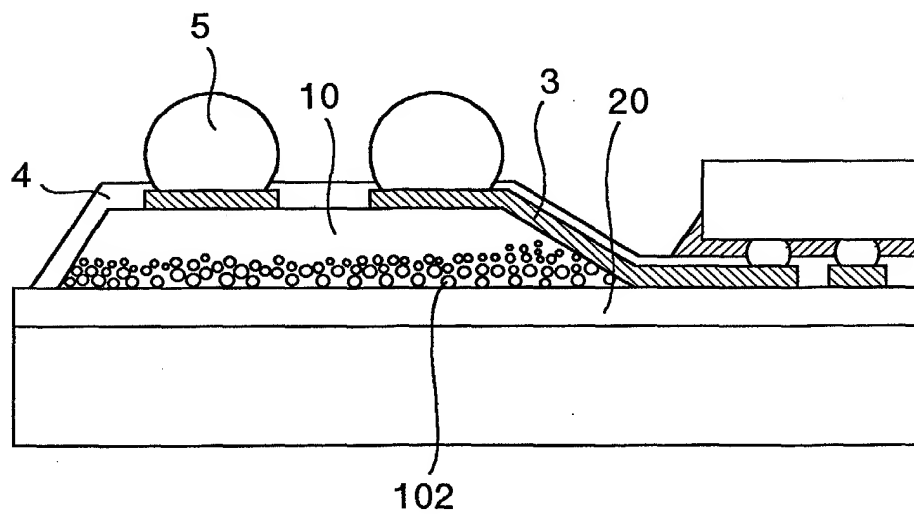


FIG.27

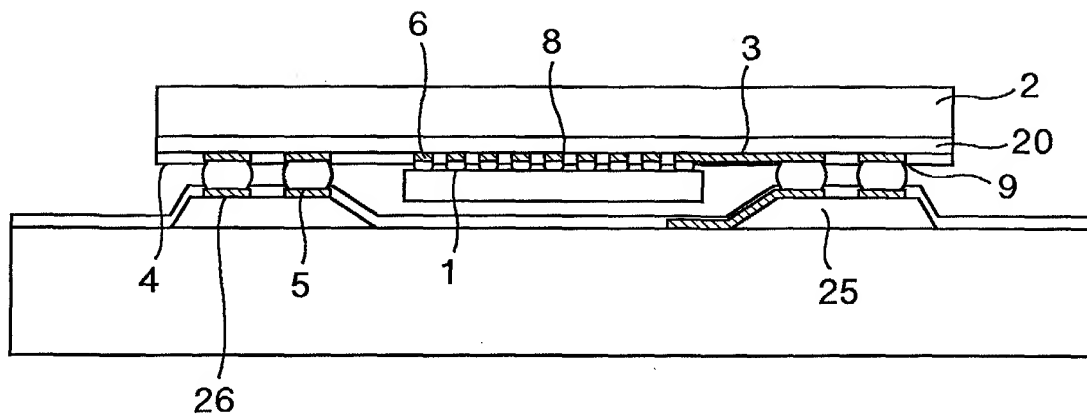


FIG.28

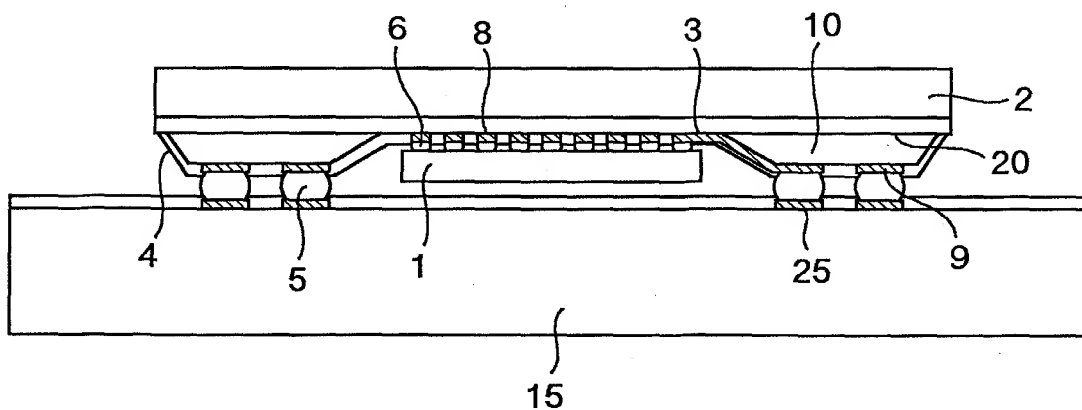


FIG.29

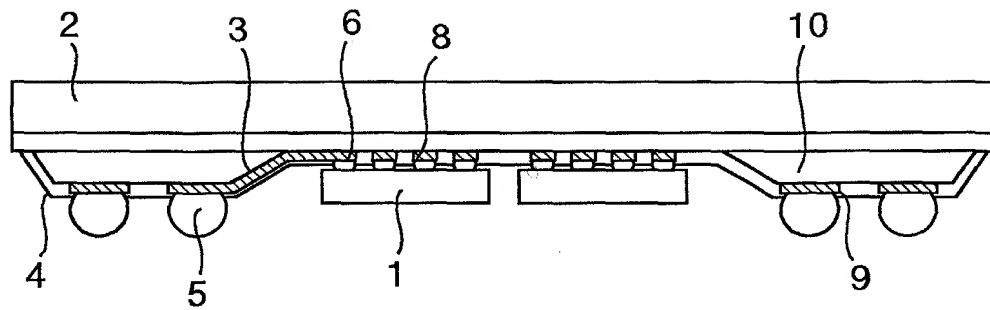


FIG.30

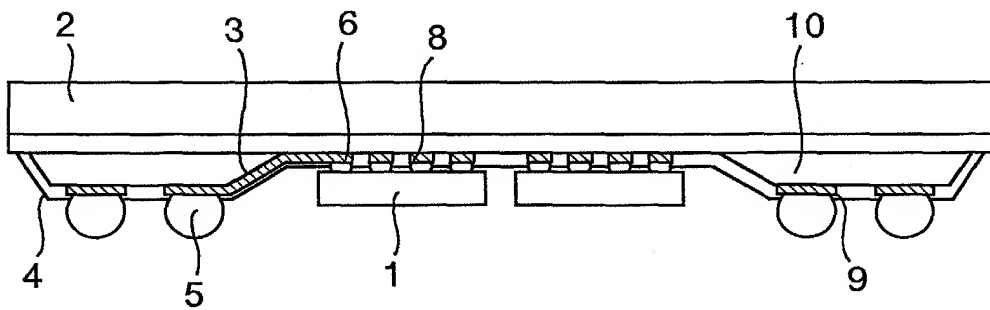


FIG.31

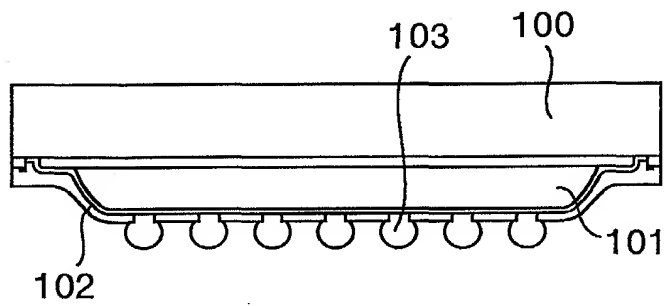


FIG.32

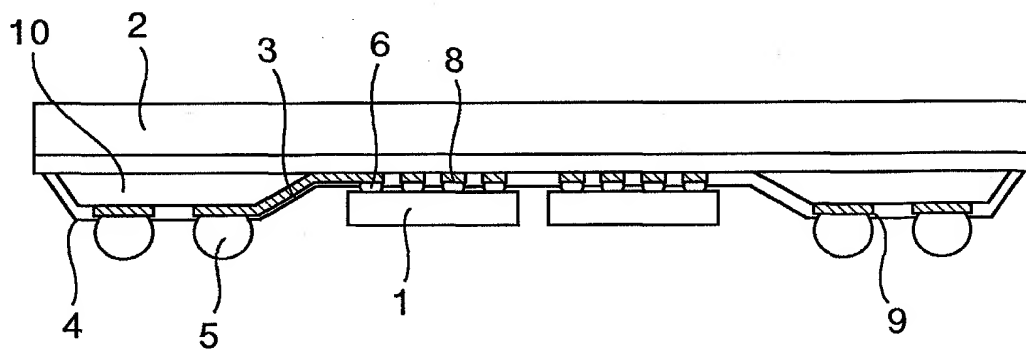


FIG.33

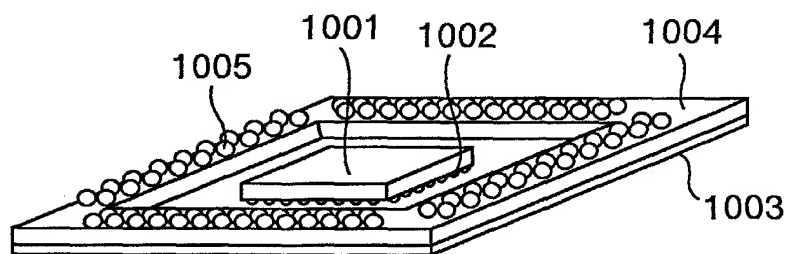
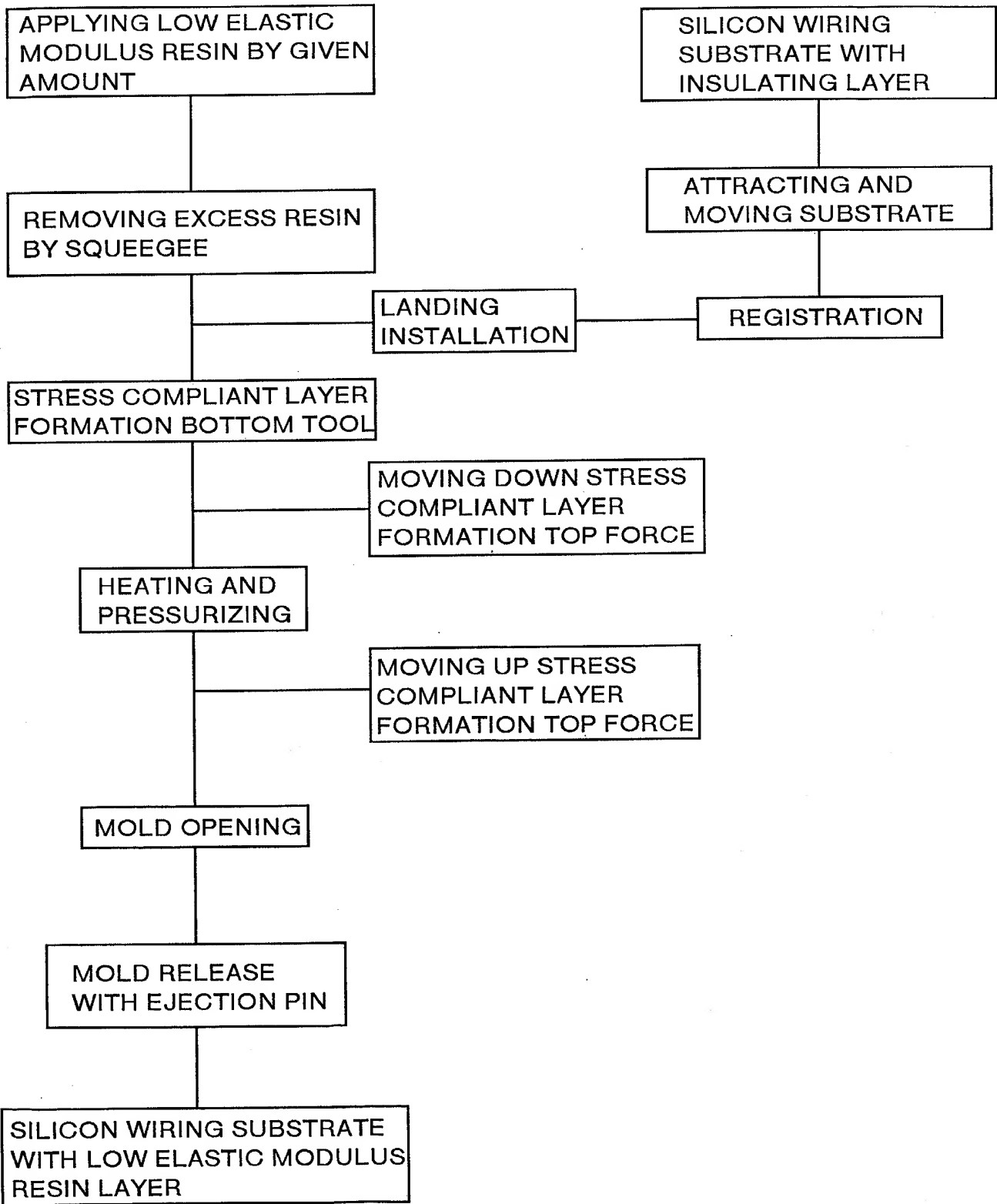


FIG.34



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FIG.35A

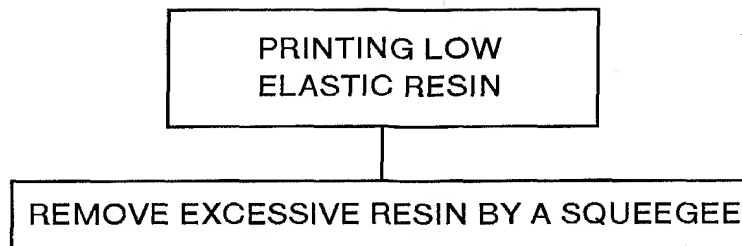


FIG.35B

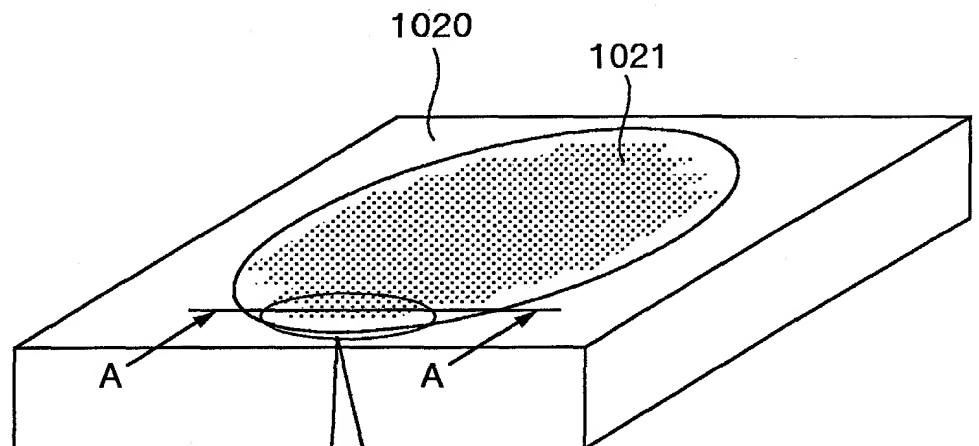


FIG.35C

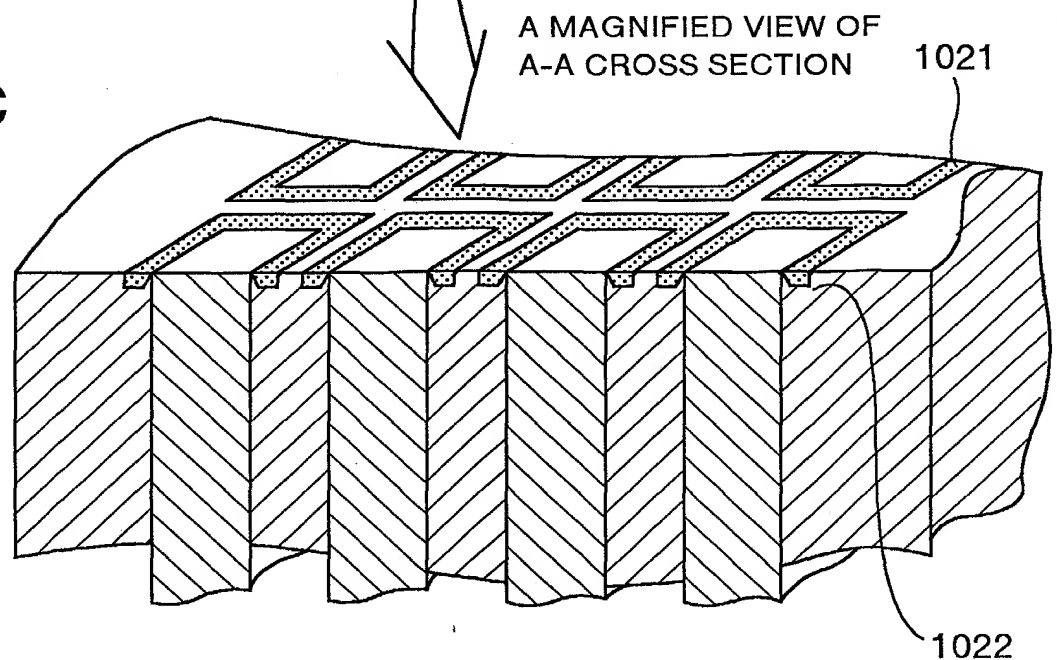


FIG.36A

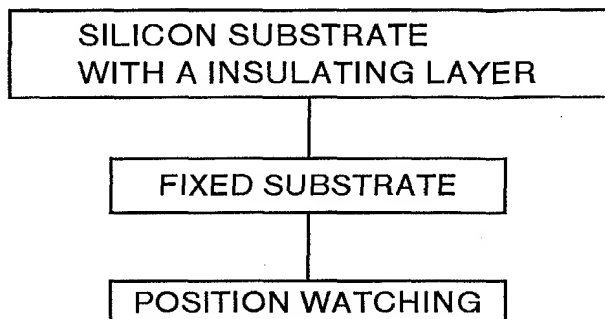


FIG.36B

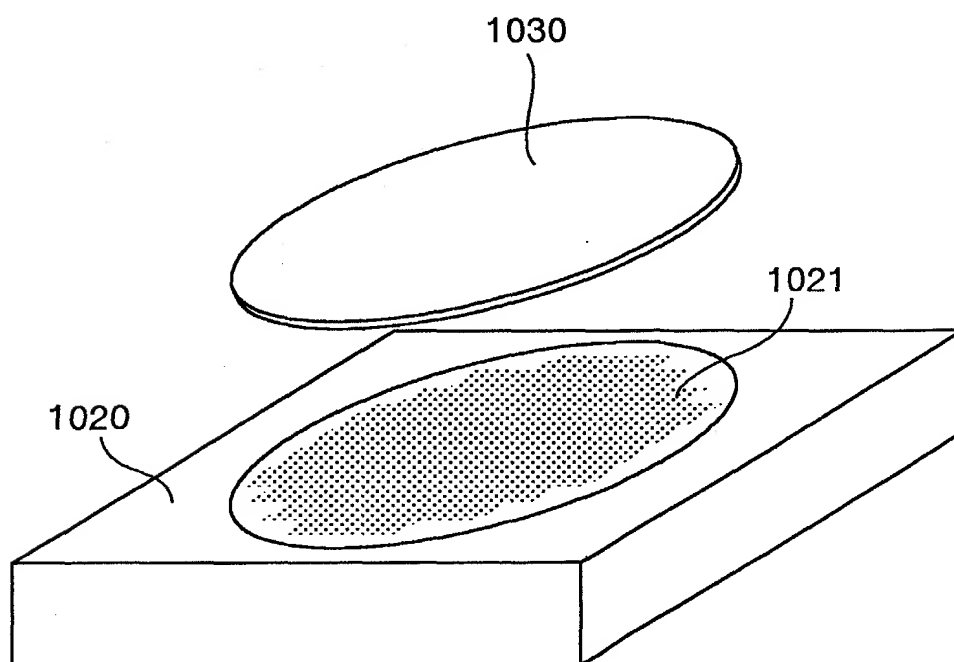


FIG.37A

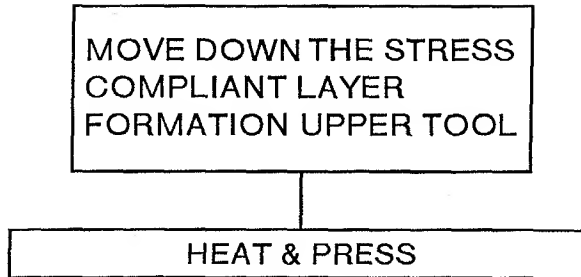


FIG.37B

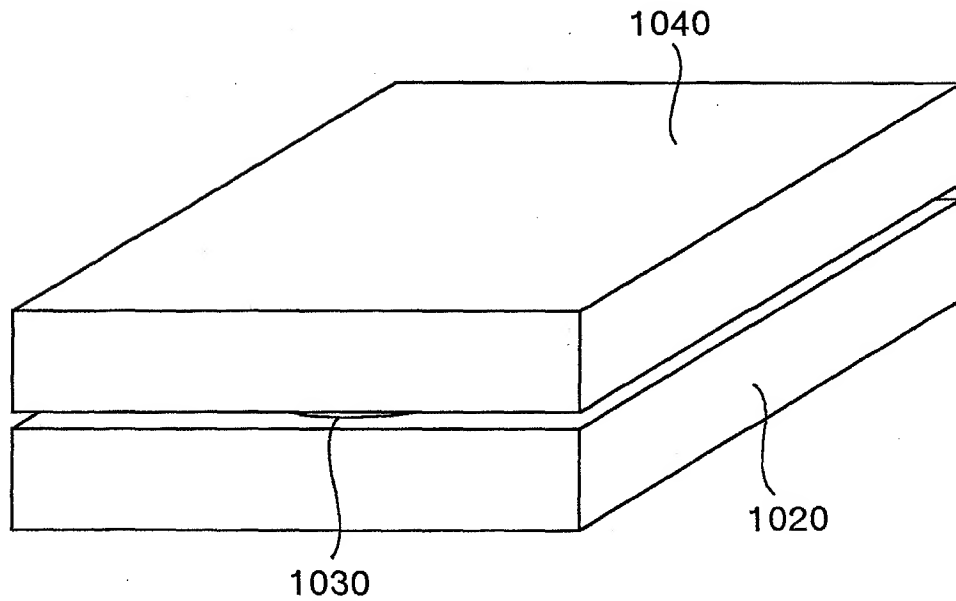


FIG.38A

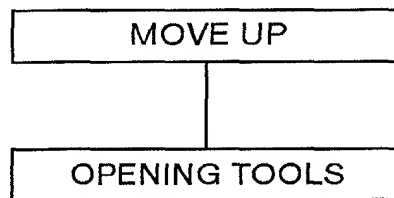


FIG.38B

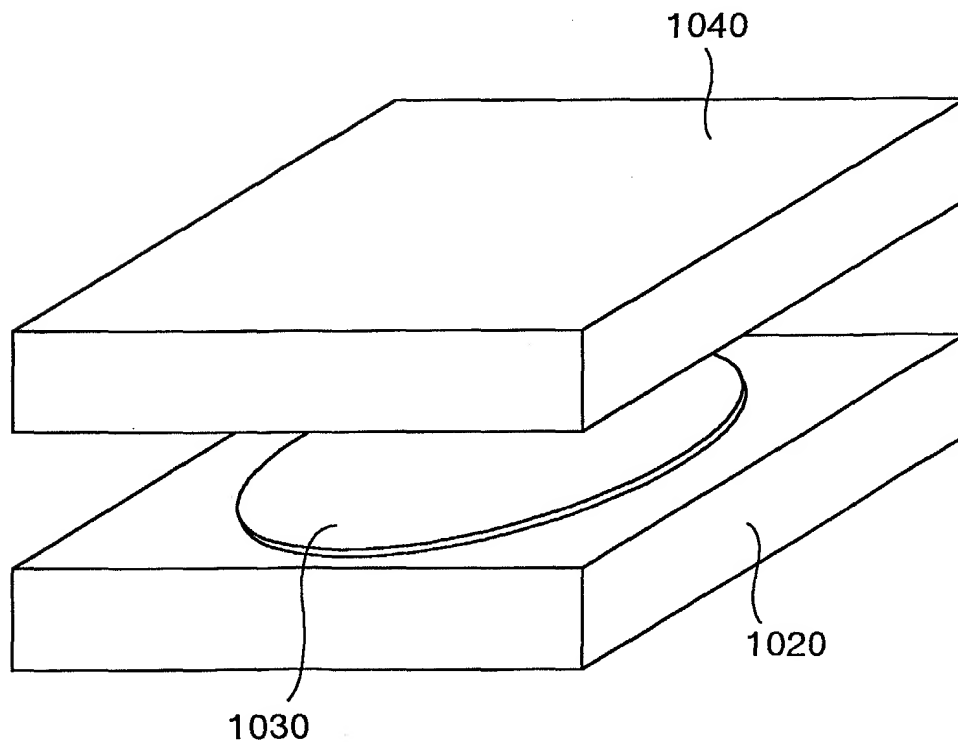
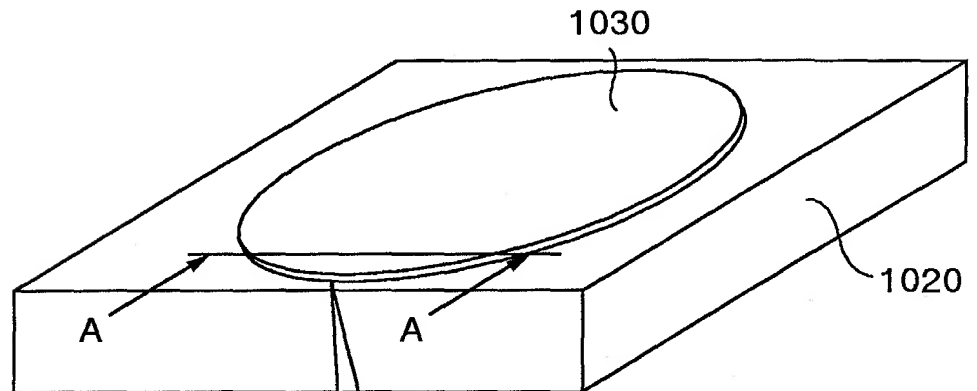


FIG.39A

RELEASED BY
EJECTER PIN

THE STRESS COMPLIANT
LAYER FORMED SILICON
SUBSTRATE

FIG.39B



A MAGNIFIED VIEW OF
A-A CROSS SECTION

FIG.39C

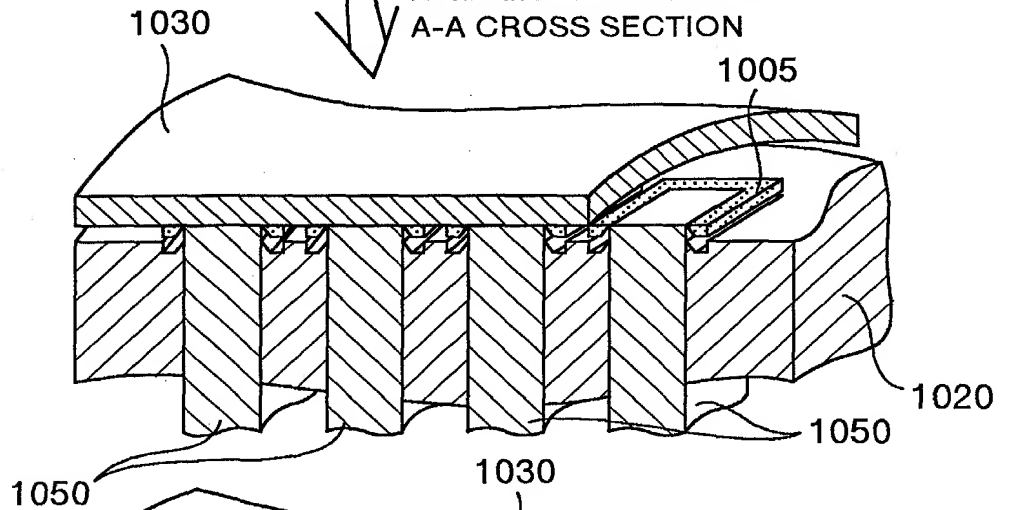


FIG.39D

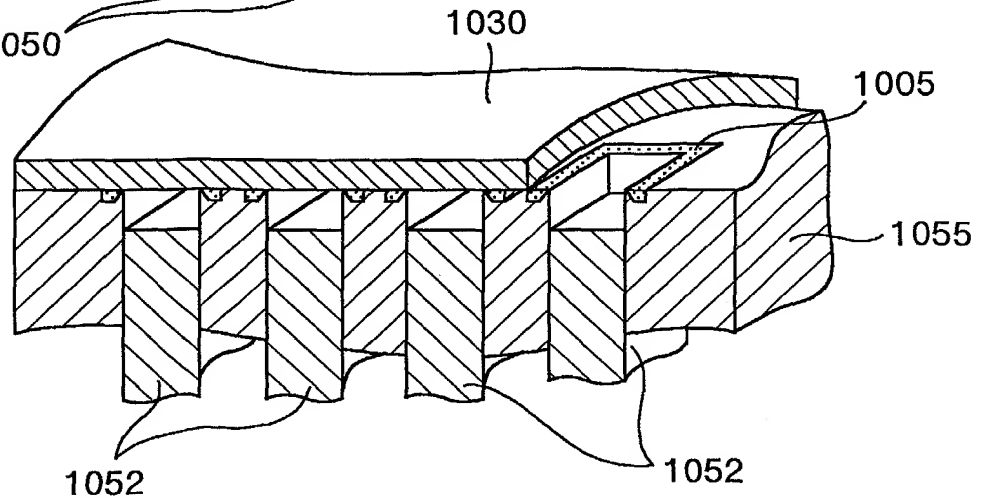


FIG.40A

THE STRESS COMPLIANT LAYER
FORMED SILICON SUBSTRATE

FIG.40B

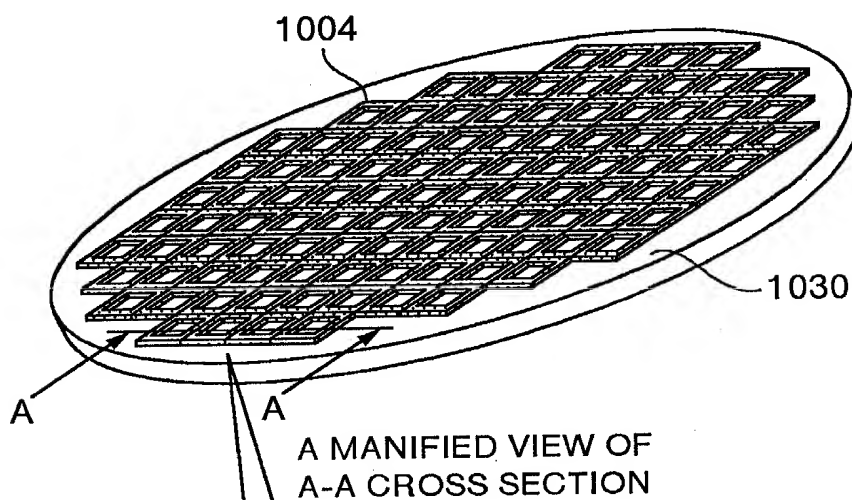


FIG.40C

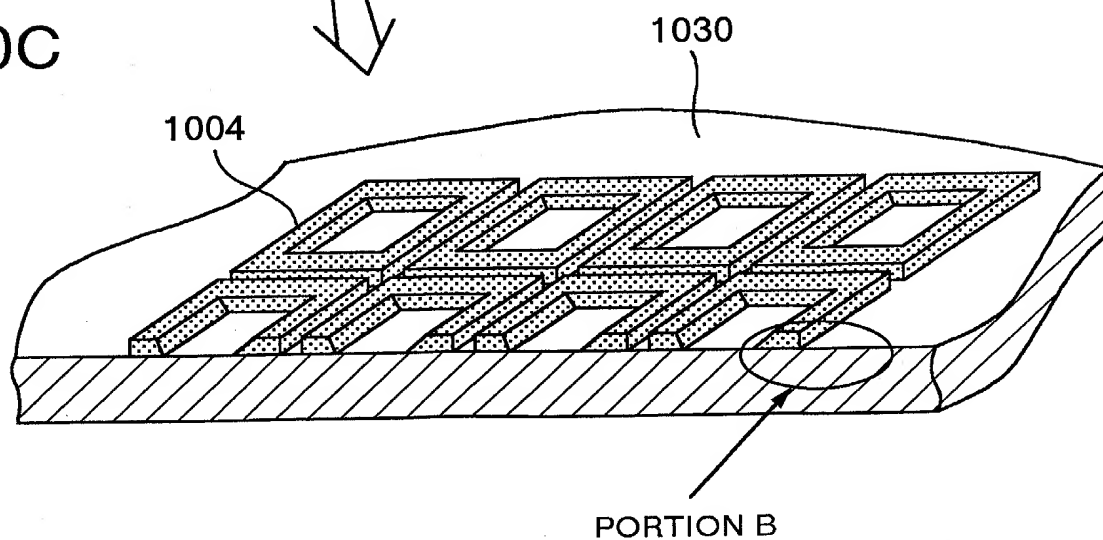


FIG.41A

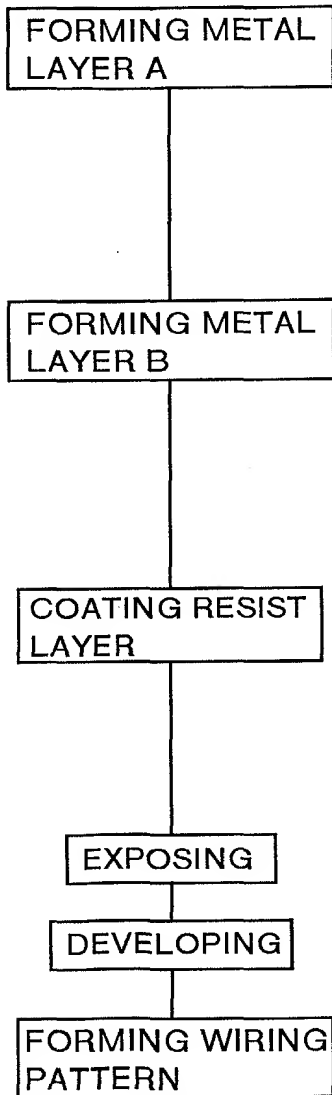


FIG.41B

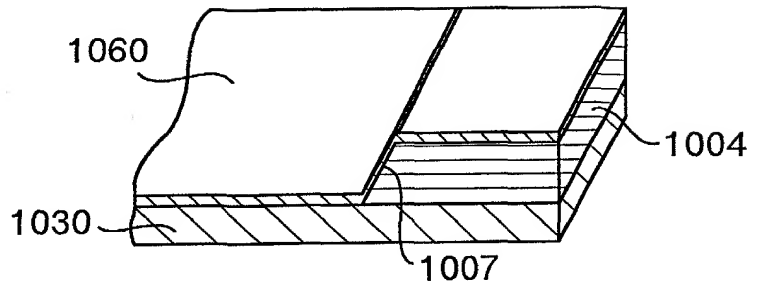


FIG.41C

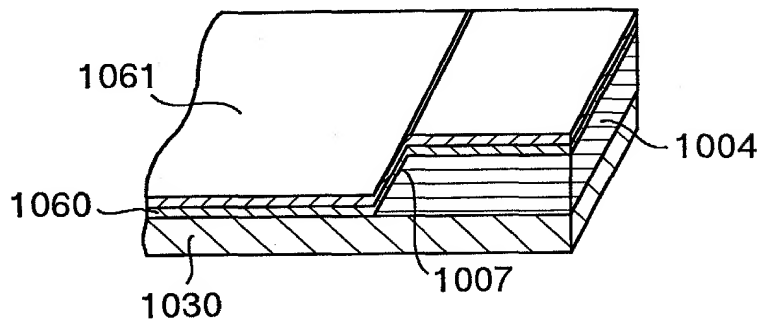


FIG.41D

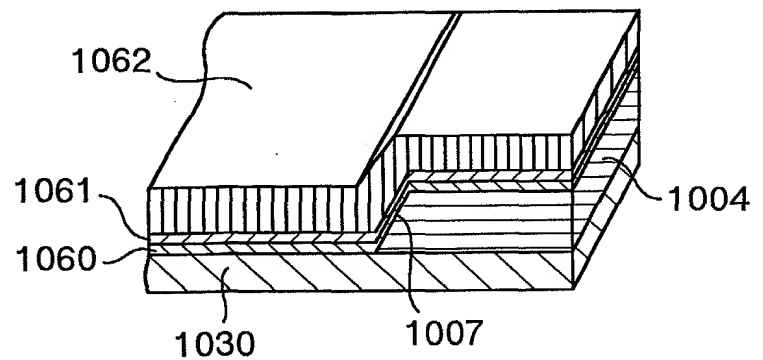


FIG.41E

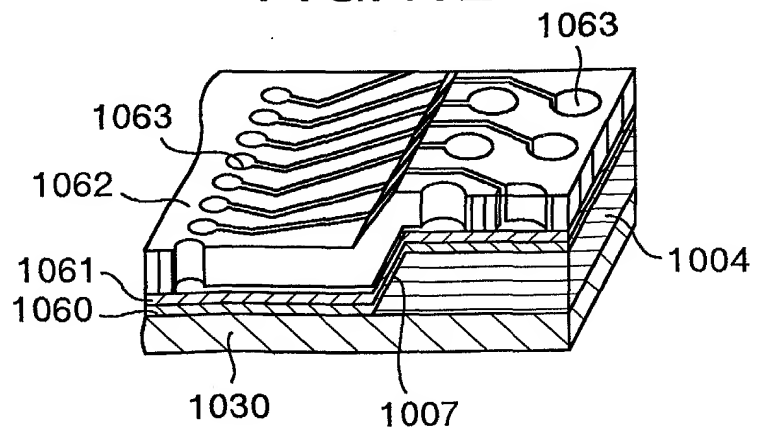


FIG.42A

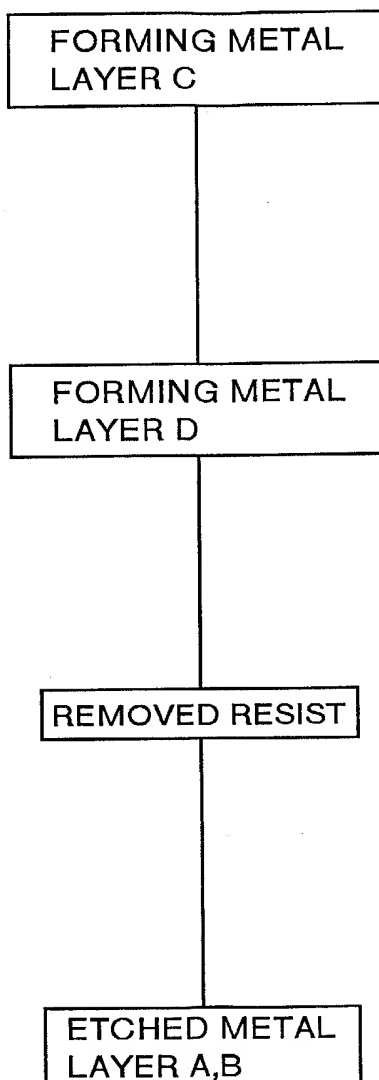


FIG.42B

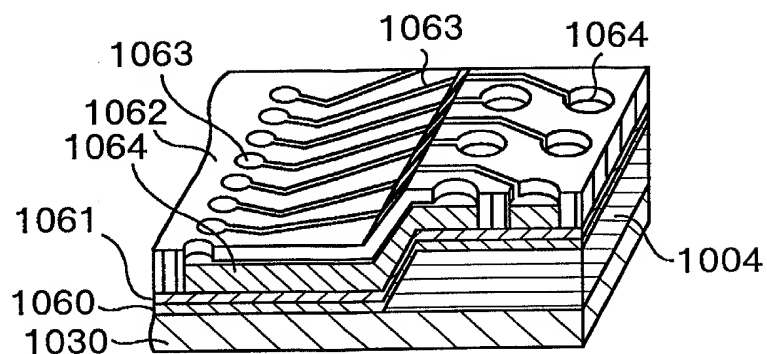


FIG.42C

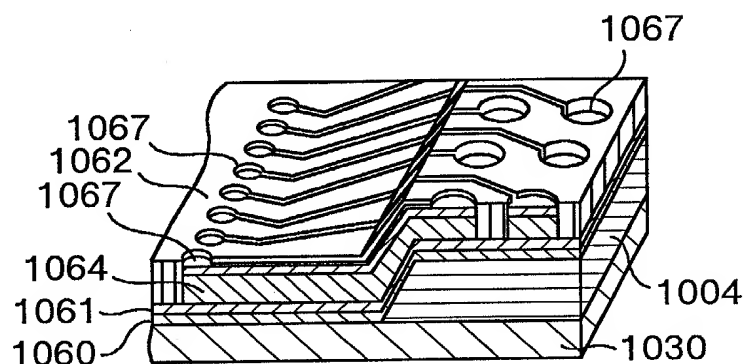


FIG.42D

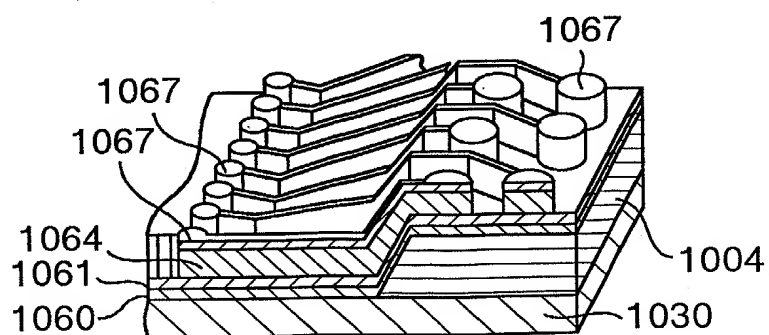


FIG.42E

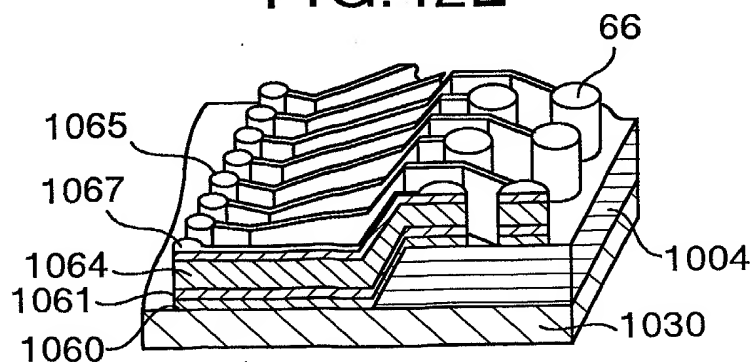


FIG.43A

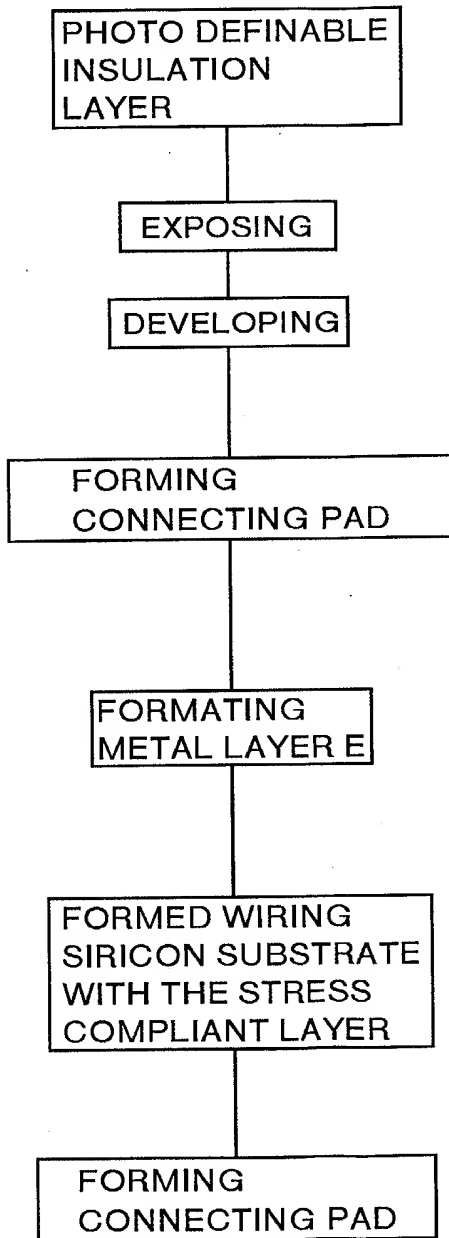


FIG.43B

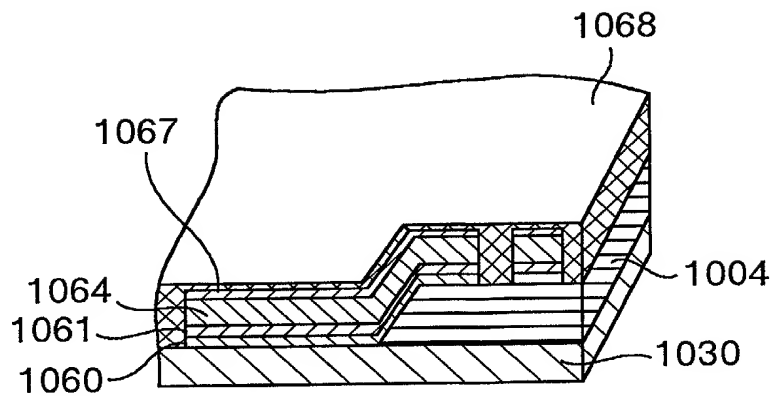


FIG.43C

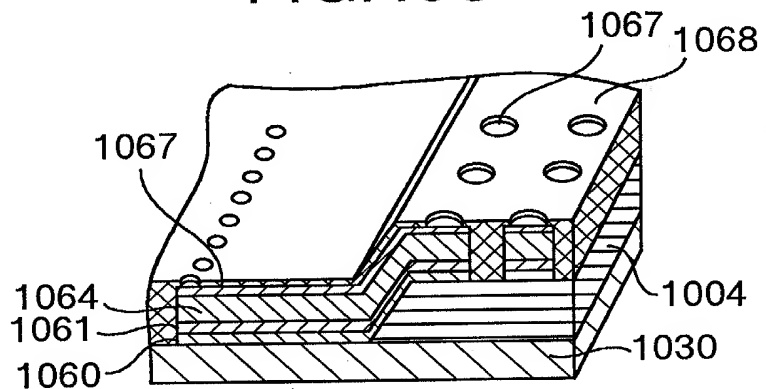


FIG.43D

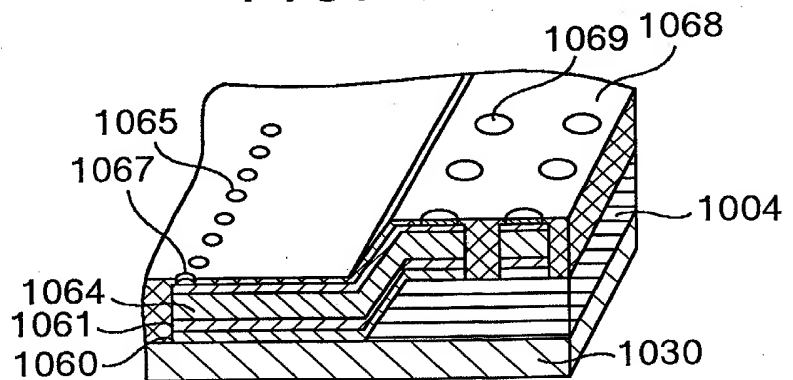


FIG.43E

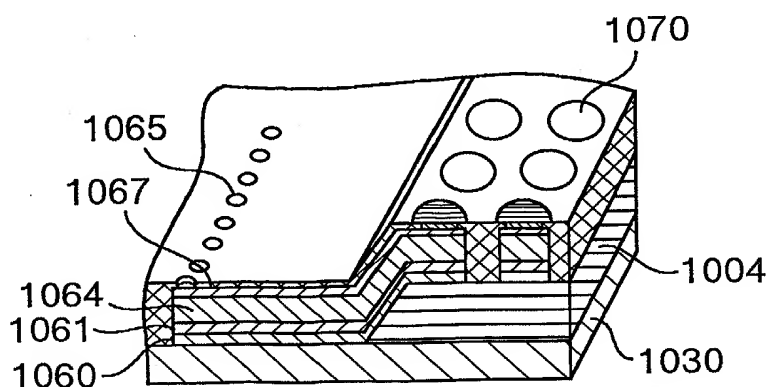


FIG.44A

FORMED WIRING
SIRICON SUBSTRATE
WITH THE STRESS
COMPLIANT LAYER

INDIVIDUAL
PIECE CUTTING

FIG.44B

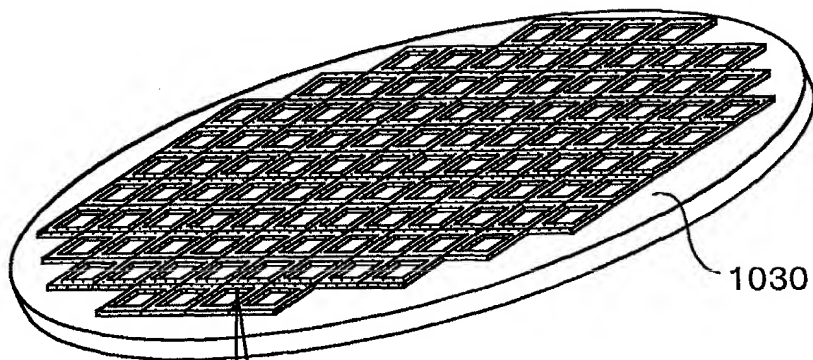


FIG.44C

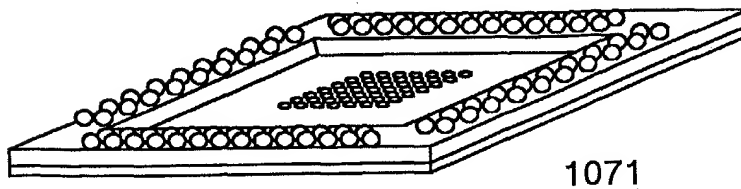


FIG.45A

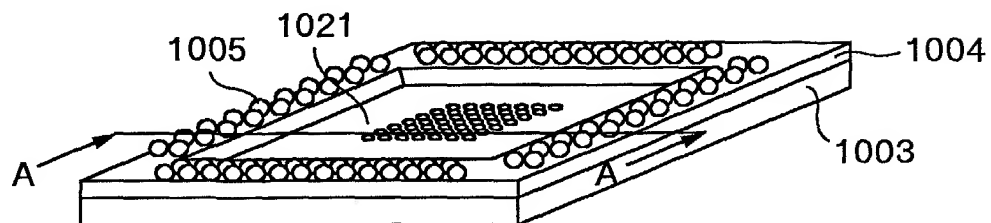


FIG.45B

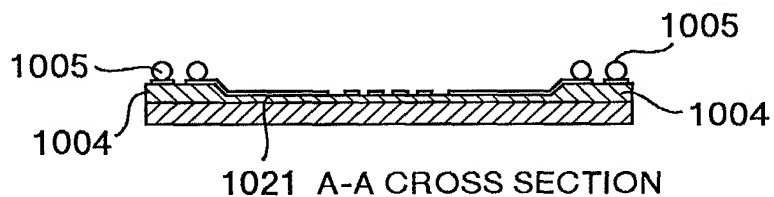


FIG.46A

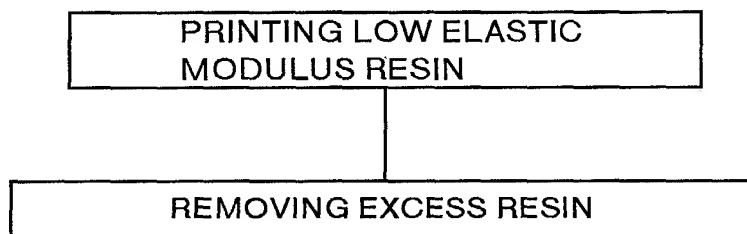


FIG.46B

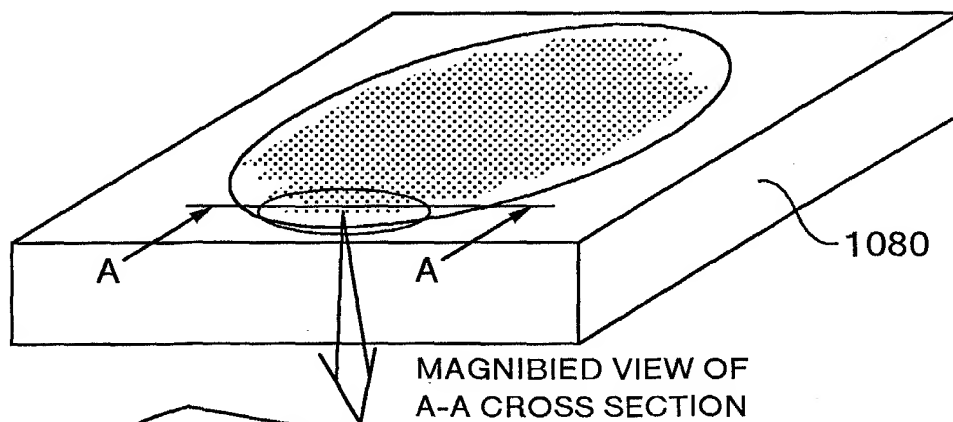


FIG.46C

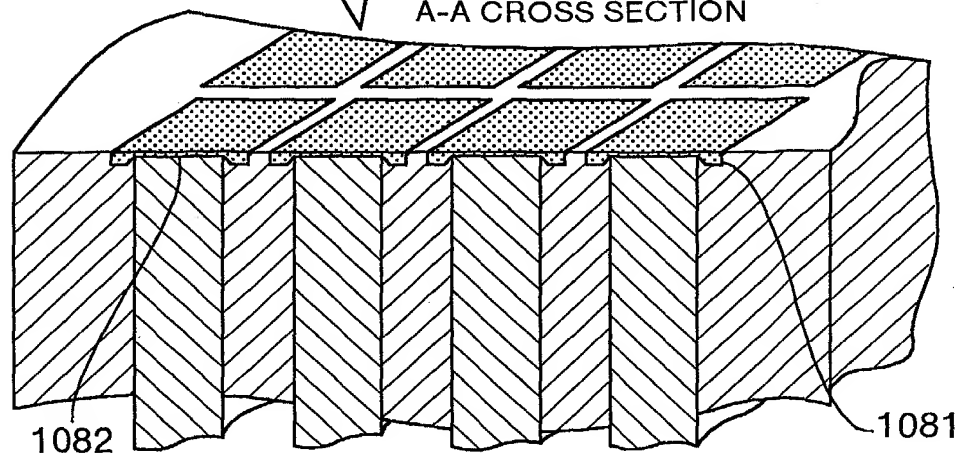


FIG.47A

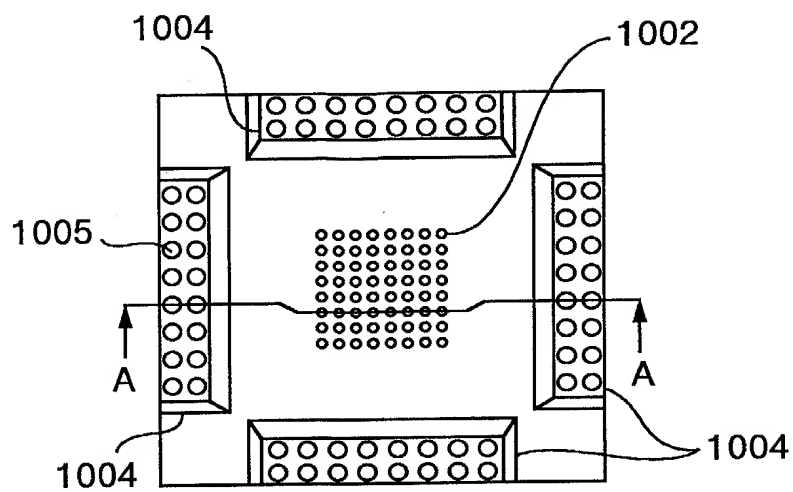


FIG.47B



FIG.48

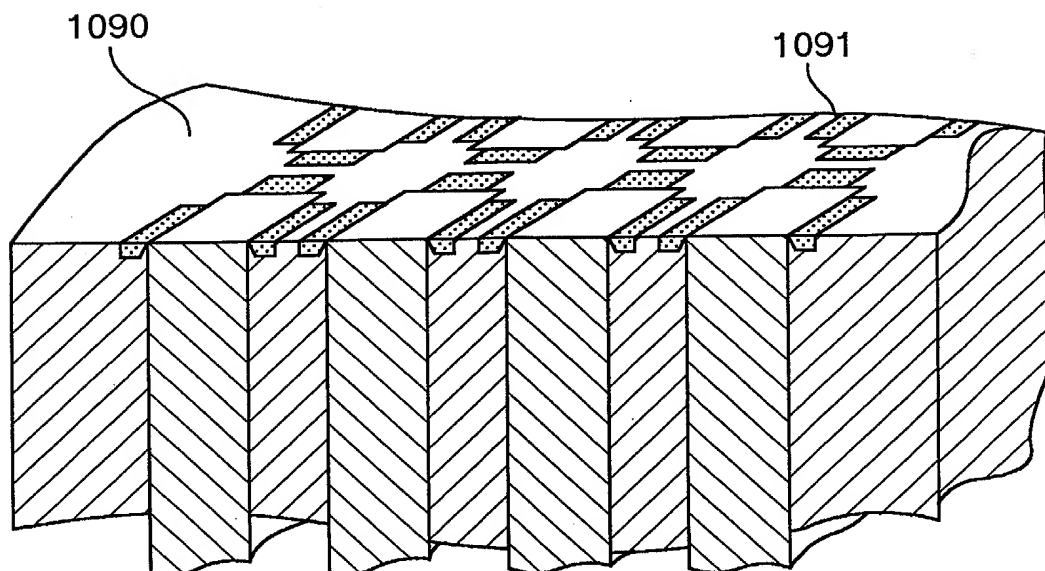


FIG.49

